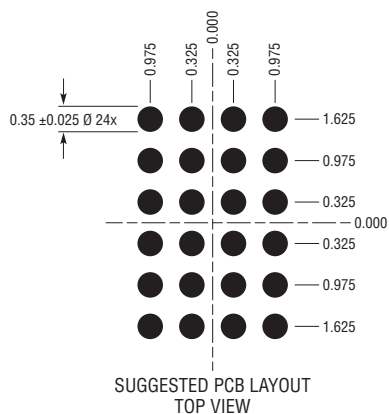
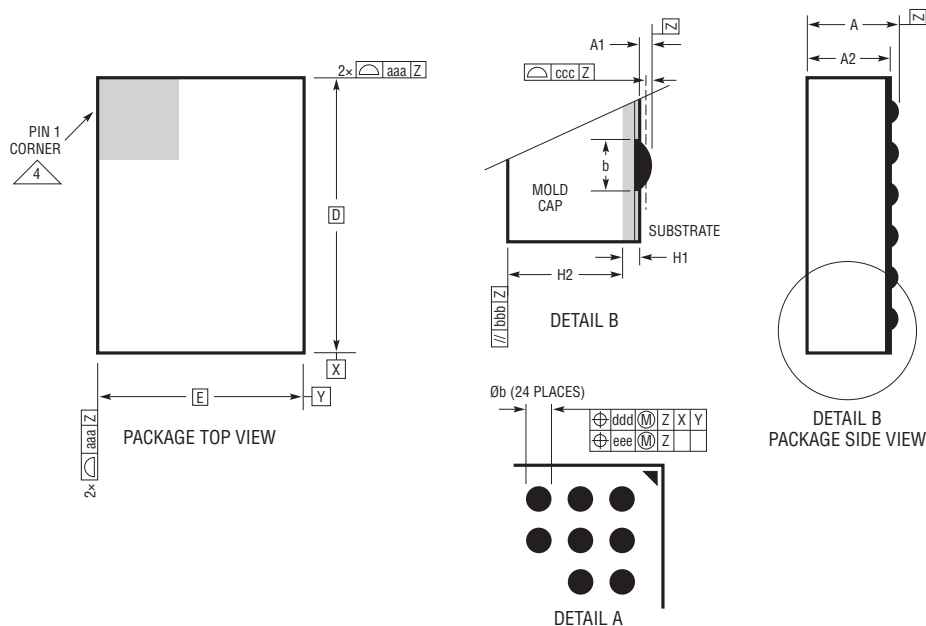


LGA Package
24-Lead (4mm × 3mm × 1.21mm)
(Reference LTC DWG# 05-08-1657 Rev 0)



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	1.09	1.21	1.33	
A1	—	—	0.05	
A2	1.09	1.18	1.27	
b	0.32	0.35	0.38	PAD DIMENSION
D		4.00		
E		3.00		
e		0.65		
F		3.25		
G		1.95		
H1		0.18 REF		SUBSTRATE THK
H2		1.00 REF		MOLD CAP HT
aaa			0.15	
bbb			0.10	
ccc			0.10	
ddd			0.15	
eee			0.08	

TOTAL NUMBER OF PADS: 24

- NOTES:**
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 2. ALL DIMENSIONS ARE IN MILLIMETERS
 3. PAD DESIGNATION PER JEP95
 4. DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN 1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
 5. PRIMARY DATUM -Z- IS SEATING PLANE
 6. PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

